Title (en)

METHOD FOR CONNECTING ELECTRONIC COMPONENTS TO A SUBSTRATE, AND A METHOD FOR CHECKING SUCH A CONNECTION

Title (de)

VERFAHREN ZUR VERBINDUNG VON ELEKTRONISCHEN BAUELEMENTEN MIT EINEM TRÄGERSUBSTRAT SOWIE VERFAHREN ZUR ÜBERPRÜFUNG EINER DERARTIGEN VERBINDUNG

Title (fr)

PROCEDE PERMETTANT DE MONTER DES COMPOSANTS ELECTRONIQUES SUR UN SUBSTRAT ET PROCEDE DE VERIFICATION DUDIT MONTAGE

Publication

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Application

EP 99953603 A 19990827

Priority

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- DE 19839760 A 19980901

Abstract (en)

[origin: DE19839760A1] The invention relates to a method for connecting electronic components to a substrate, whereby at least one terminal contact of the component is connected in an electrically conductive manner to at least one terminal contact on the upper side of the substrate by depositing a solder bump on at least one of the terminal contacts to be connected. The component is precisely connected to the substrate, and the at least one solder bump is soldered in order to moisten the contact surfaces. The invention provides that, during soldering, the at least one solder bump (24) is deformed in the plane of contact such that a degree of deformation is obtained which permits a two-dimensional evaluation of the degree of deformation by analyzing a radiograph of the connection point.

IPC 1-7

H01L 21/60; H01L 21/66

IPC 8 full level

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C-Set (source: EP US)

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